

AMENDMENTS TO THE CLAIMS

1. - 11. (Previously Cancelled)

12. (Currently Amended) A semiconductor structure package comprising:

a substrate having an upper surface, and a lower surface, ~~and an edge region disposed between said upper and lower surfaces, said edge including a first cut portion and a second broken portion comprising a sheared portion~~ one of said upper surface and said lower surface including at least one groove capable of being broken to separate the substrate into a plurality of segments.

13. (Currently Amended) A semiconductor structure package as defined in claim 12 wherein said ~~cut portion~~ at least one groove further comprises a sawn portion.

14. (Currently Amended) A semiconductor structure package as defined in claim 12 wherein said ~~cut portion~~ at least one groove further comprises a scribed portion.

15. (Currently Amended) A semiconductor structure package as defined in claim 12 wherein said ~~cut portion~~ at least one groove further comprises a chemically etched portion.

16. (Currently Amended) A semiconductor structure package as defined in claim 12 wherein said ~~cut portion~~ at least one groove further comprises a milled portion.

17- 27. (Previously Cancelled)